RZ/G3S

AWO Example Project Start-up Guide

Introduction

This application note describes how to set up and execute RZ/G3S AWO Example Project.

Target Device

RZ/G3S

Contents

1. Specifications

1.1 Deliverables

Table 1-1. Deliverables of AWO Example Project

Deliverables	File name	Description
RZ/G3S AWO Example Project	freertos_w_awo_rzg3s_evk_example.zip	CM33 project file for e2studio
RZ/G3S AWO Example Project Start-up Guide	r01an7396ej0420_rzg3s_awo_example_project_start-up_guide.pdf	This material.

2. Proven Environment

Table 2-1. Proven Environment of AWO Example Project

Item	Contents
Integration Development Environment	e² studio 2026-07 or later
RZ/G VLP	v3.0.7 update5 and v4.0.1
RZ Flexible Software Package (FSP)	v4.2.0

3. AWO Example Project Setup

3.1 RZ FSP Setup

Please refer to Getting Started with RZ/G Flexible Software Package.

3.2 RZ/G VLP Setup

3.2.1 Using RZ/G VLP v3.0.7

This section described how to integrate AWO related stuff to RZ/G VLP v3.0.7-update5.

1. Follow the procedure from the beginning of **2.2 Building Images** to **(3) Add layers** of **SMARC EVK of RZ/G3S Linux Start-up Guide**.

2. Download Multi-OS Feature Package (r01an8260ej0420-rz-multi-os-pkg.zip) to your working directory and run the commands stated below:

```
$ cd ~/rzg_vlp_<pkg ver>
$ unzip <Multi-OS download dir>/r01an8260ej0420-rz-multi-os-pkg.zip
$ tar zxvf r01an8260ej0420-rz-multi-os-pkg/meta-rz-features_multi-os_v4.2.0.tar.gz
```

3. Uncomment the following line in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg3s/meta-rzg3s-vlp3/conf/layer.conf** for enabling AWO support:

```
#MACHINE_FEATURES_append = " RZ_REMOTEPROC"
MACHINE_FEATURES_append = " RZ_CM33_FIRMWARE_LOAD"
#MACHINE_FEATURES_append = " RZ_CM33_COLDBOOT"
MACHINE_FEATURES_append = " RZ_AWO_SUPPORT"
```

4. Add the layer for Multi-OS Package, simply run the helper script and select the **meta-rzg3s-vlp3** layer from the list.

```
$ cd build
$ bash ../meta-rz-features/meta-rz-multi-os/add_meta_layer.sh
```

6. Continue to set up VLP by following **(4) - (5) of 2.2 Building images** in **SMARC EVK of RZ/G3S Linux Start-up Guide**.

3.2.2 Using RZ MPU VLP v4.0.1

This section described how to integrate AWO related stuff to RZ MPU VLP v4.0.1.

1. Follow the procedure from the beginning of **2.2 Building Images** to **(3) Add layers** of **SMARC EVK of RZ/G3S Linux Start-up Guide**.

2. Download Multi-OS Feature Package (r01an8260ej0420-rz-multi-os-pkg.zip) to your working directory and run the commands stated below:

```
$ cd ~/rzg_vlp_<pkg ver>
$ unzip <Multi-OS download dir>/r01an8260ej0420-rz-multi-os-pkg.zip
$ tar zxvf r01an8260ej0420-rz-multi-os-pkg/meta-rz-features_multi-os_v4.2.0.tar.gz
```

3. Uncomment the following line in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg3s/meta-rzg3s-vlp4/conf/layer.conf** for enabling AWO support:

```
#MACHINE_FEATURES:append = " RZ_REMOTEPROC"
MACHINE_FEATURES:append = " RZ_CM33_FIRMWARE_LOAD"
#MACHINE_FEATURES:append = " RZ_CM33_COLDBOOT"
MACHINE_FEATURES:append = " RZ_AWO_SUPPORT"
```

4. Add the layer for Multi-OS Package, simply run the helper script and select the **meta-rzg3s-vlp4** layer from the list.

```
$ cd build
$ bash ../meta-rz-features/meta-rz-multi-os/add_meta_layer.sh
```

5. Continue to set up VLP by following **(4) - (5) of 2.2 Building images** in **SMARC EVK of RZ/G3S Linux Start-up Guide**.

3.3 Note for Intergration

By default, all clock-related configuration is handled on the Linux (main core) side. If the system design is changed such that clocks for specific drivers are configured by the RTOS (sub core) side, the implementation must be customized to ensure these settings do not conflict with Linux's clock initialization sequence.

The peripherals which are NOT enabled enter Module Standby Mode after Linux kernel is booted up. That means the peripherals used on sub core (CM33) side might stop working at that time. To avoid such a situation, Multi-OS Package incorporates the patch below:

- 0001-Set-SCIF1-and-OSTM1-OSTM2-as-critical-clock.patch

This patch prevents SCIF channel 1 and GTM channel 1, 2 used in RPMsg demo program from entering Module Standby Mode. If you have any other peripherals which you would like to stop entering Module Standby implicitly, please apply the patch as shown below:

```
diff --git a/drivers/clk/renesas/r9a08g045-cpg.c b/drivers/clk/renesas/r9a08g045-cpg.c
index 33a204fbe25c..dba2b4925e66 100644
--- a/drivers/clk/renesas/r9a08g045-cpg.c
+++ b/drivers/clk/renesas/r9a08g045-cpg.c
@@ -381,6 +381,9 @@ static const unsigned int r9a08g045_crit_mod_clks[] __initconst = {
  MOD_CLK_BASE + R9A08G045_IA55_CLK,
  MOD_CLK_BASE + R9A08G045_DMAC_ACLK,
  MOD_CLK_BASE + R9A08G045_VBAT_BCLK,
+ MOD_CLK_BASE + R9A08G045_SCIF1_CLK_PCK,
+ MOD_CLK_BASE + R9A08G045_OSTM1_PCLK,
+ MOD_CLK_BASE + R9A08G045_OSTM2_PCLK,
+ MOD_CLK_BASE + R9A08G045_xxxx,
  };
```

With respect to the allowable value for **xxxx**, please refer to the link below:

- https://github.com/renesas-rz/rz_linux-cip/blob/f12a03d8f2cf971734190c35aeaac98dde815b2d/drivers/clk/renesas/r9a08g045-cpg.c#L210-L296

3.4 How to build AWO Example Project

Here is the procedure to build AWO Example Project:

1. Deploy and boot up Linux by following 3. Preparing the SD Card, 4. Reference Board Setting and 5. Booting and Running Linux of **SMARC EVK of RZ/G3S Linux Start-up Guide**.
2. Extract **freertos_w_awo_rzg3s_evk_example.zip** on your development PC.
3. Launch e^2 studio and click **File** > **Import**.

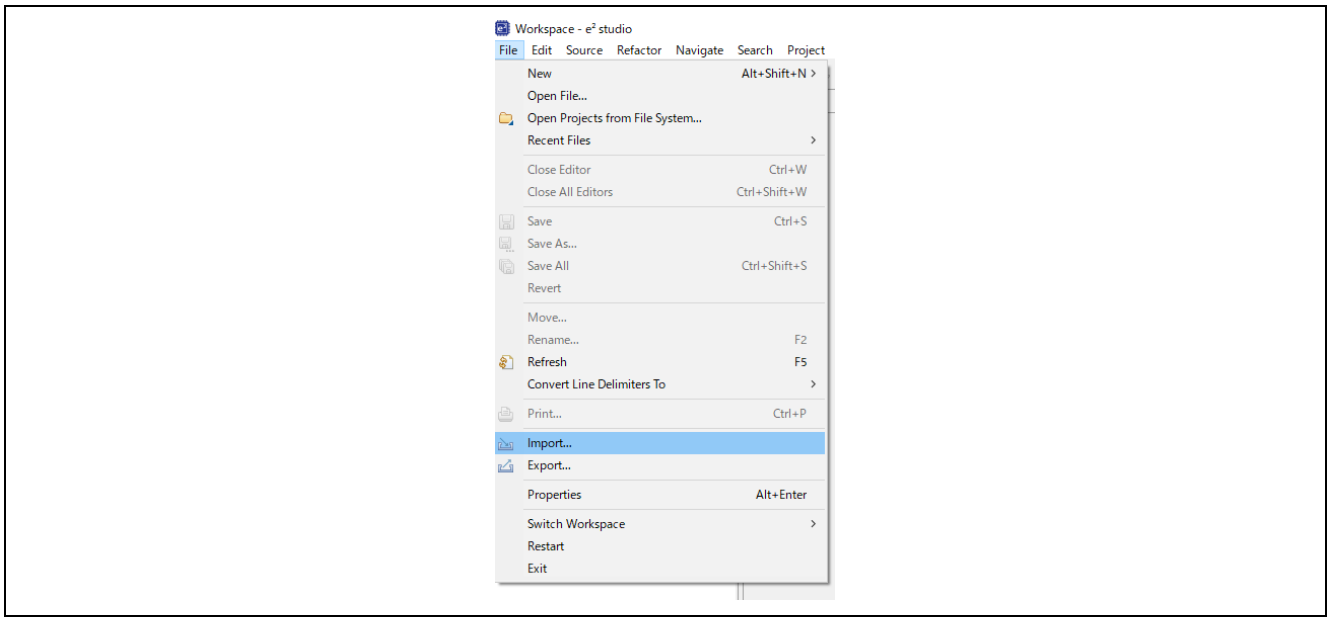

Figure 3.1 Import of CM33 AWO Example Project (1)

4. Select Existing Projects into Workspace and click Next >.

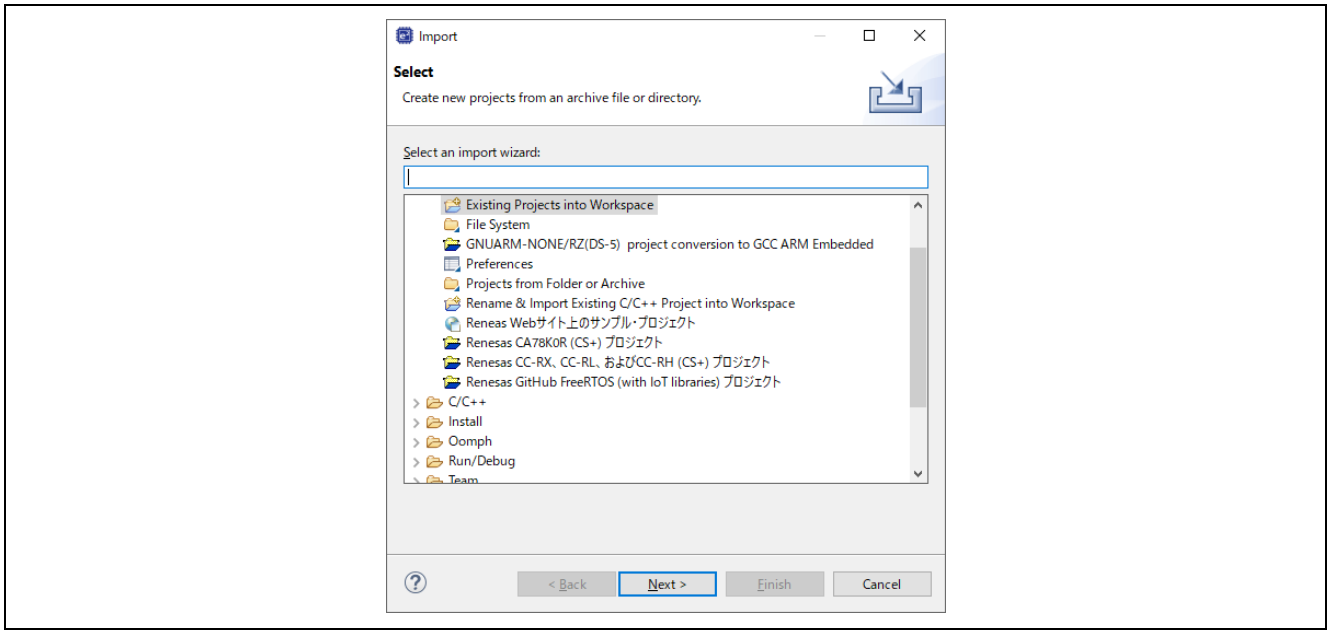

Figure 3.2 Import of CM33 AWO Example Project (2)

5. Input the path to the directory where **freertos_w_awo_rzg3s_evk_example** project was extracted and click **Finish**.

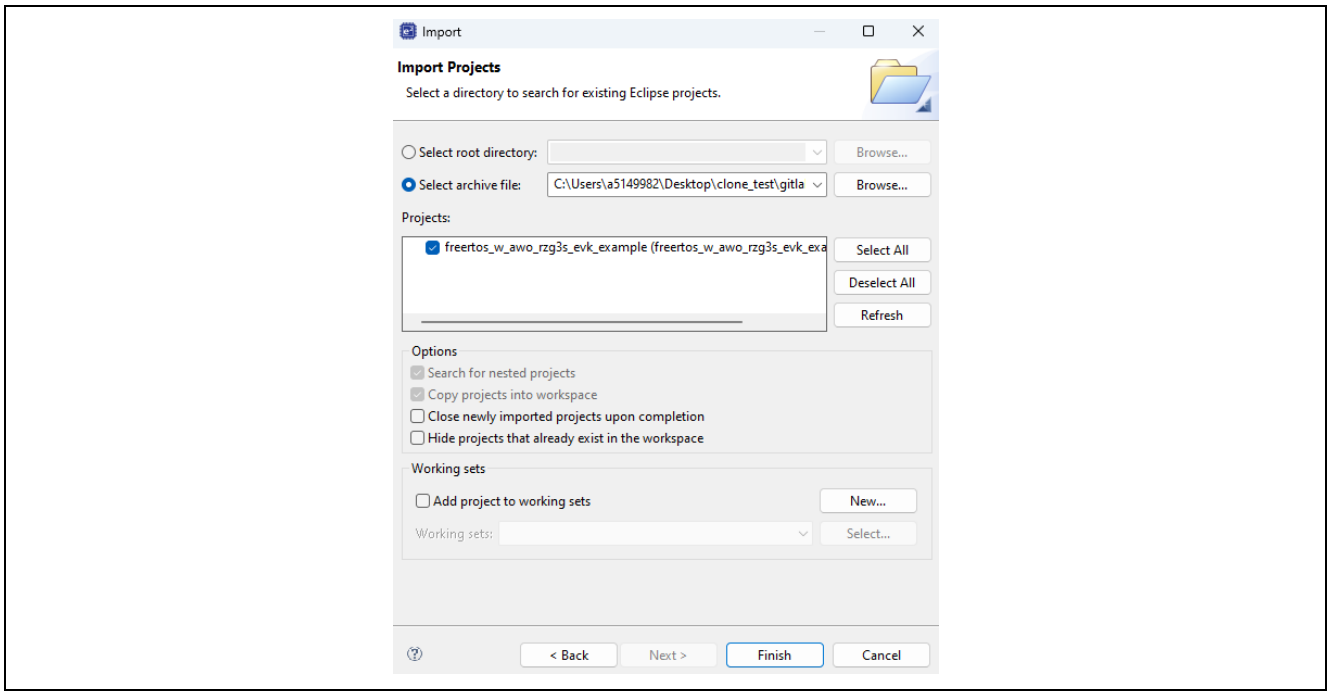

Figure 3.3 Import of CM33 AWO Example Project (3)

6. Build **freertos_w_awo_rzg3s_evk_example** project from **Project** > **Build All** or **Build Project**.

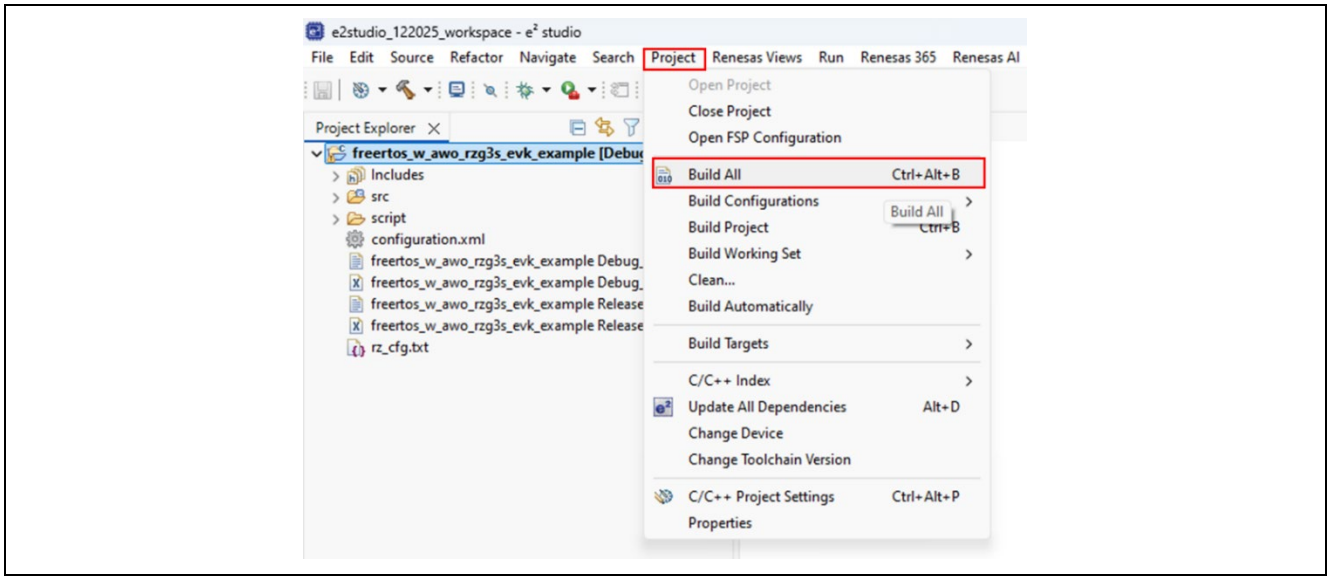

Figure 3.4 Build CM33 AWO Example Project

7. If the build is successfully completed, you can see the build artifact in **Debug** or **Release** directory as stated below:

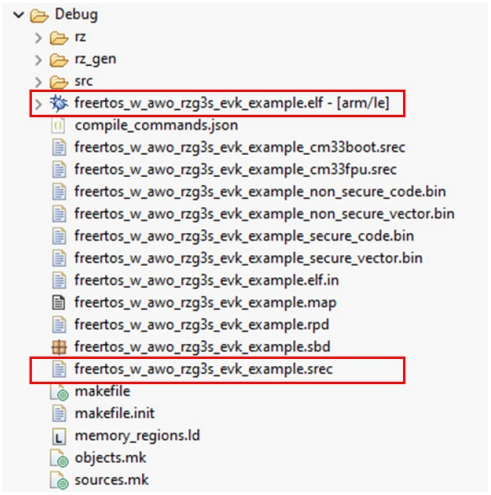

Figure 3.5 Build Artifact of CM33 AWO Example Project

3.5 How to deploy AWO Example Project

This section describes how to deploy the AWO example program built in the previous chapter to the board.

To write to the SPI flash on the board, use the Flash Writer in the RZ/G VLP Linux package.

3.5.1 For QSPI boot (1.8V)

1. Follow the procedure from the beginning of **4 Reference Board Setting** to **4.4 Write the Bootloader of RZ/G3S Linux Start-up Guide**.

2. Program **freertos_w_awo_rzg3s_evk_example.srec** with Flash Writer as shown below:

```
> xls2
===== Qspi writing of RZ/G2 Board Command =============
Load Program to Spiflash
Writes to any of SPI address.
Program size & Qspi Save Address
===== Please Input Program Top Address ============
  Please Input : H'80200000

===== Please Input Qspi Save Address ===
  Please Input : H'200000
please send ! ('.' & CR stop load)
Erase SPI Flash memory...
Erase Completed
Write to SPI Flash memory.
======= Qspi  Save Information  =================
SpiFlashMemory Stat Address : H'00200000
SpiFlashMemory End Address  : H'0020D16E
============================================================
```

3. Continue to set up board by following **4.5 Change Back to Normal Boot Mode** in **SMARC EVK of RZ/G3S Linux Start-up Guide**.

3.5.2 For eMMC boot (1.8V)

1. Follow the procedure from the beginning of **8.2 How to boot from eMMC** to **Send the data of "fip-smarc-rzg3s.srec"** in **8.2.1 Writing Bootloader for eMMC Boot**.

2. Program **freertos_w_awo_rzg3s_evk_example.srec** with Flash Writer as shown below:

```
> EM_W
EM_W Start --------------
-----------------------------------------------------------
Please select,eMMC Partition Area.
 0:User Partition Area    : 62160896 Kbytes
  eMMC Sector Cnt : H'0 - H'0768FFFF
 1:Boot Partition 1       : 32256 Kbytes
  eMMC Sector Cnt : H'0 - H'0000FBFF
 2:Boot Partition 2       : 32256 Kbytes
  eMMC Sector Cnt : H'0 - H'0000FBFF
-----------------------------------------------------------
  Select area(0-2)>1
-- Boot Partition 1 Program ---------------------------
Please Input Start Address in sector :1000
Please Input Program Start Address : 80200000
Work RAM (H'00020000-H'000FFFFF) Clear....
please send ! ('.' & CR stop load)
```

3. Continue to set up board by following **8.2.1 Writing Bootloader for eMMC Boot**.

4. AWO Example Program Invocation

This chapter describes how AWO Example Program works.

1. Boot up Linux kernel.
2. Login as **root**.

```
smarc-rzg3s login: root
```

3. Invoke the commands below on Linux console to move Linux to Suspend to RAM (S2R):

```
root@smarc-rzg3s:~# echo deep > /sys/power/mem_sleep
root@smarc-rzg3s:~# echo mem > /sys/power/state
```

4. When Linux successfully moves to S2R, you should see the following display on Linux console:

```
[ 1082.105386] PM: suspend entry (deep)
[ 1082.109183] Filesystems sync: 0.000 seconds
[ 1082.122622] Freezing user space processes ... (elapsed 0.001 seconds) done.
[ 1082.131266] OOM killer disabled.
[ 1082.134496] Freezing remaining freezable tasks ... (elapsed 0.001 seconds) done.
[ 1082.143134] printk: Suspending console(s) (use no_console_suspendto debug)

CM33:Init PMIC for AWO mode
CM33:AWO Mode

Hit any key to go to ALLON mode.
```

RZ/G3S now moves to AWO, and only CM33 AWO Example Project can work. (Note)

Note: On Linux console, Line Feed (LF) should be specified as New Line Code.

5. When typing any key on Linux Console, RZ/G3S starts to move to ALLON, and Linux should be resumed as shown below:

```
Hit any key to go to ALLON mode.
a
CM33:Set GreenPAKto ALLON
NOTICE: BL2: v2.7(release):2.7.0/g3s_1.0.0_rc4
NOTICE: BL2: Built : 11:52:53, Feb 292024
NOTICE: BL2: Booting BL31
[ 60.710450] ehci-platform 11e30100.usb: port 1 resume error -110
[ 60.836140] usbusb2-port1: device 2-1 not suspended yet
[ 60.880506] Disabling non-boot CPUs ...
[ 60.899495] Microchip KSZ9131 Gigabit PHY 11c30000.ethernet-ffffffff:07: attached PHY driver
[Microchip KSZ9131 Gigabit PHY] (mii_bus:phy_addr=11c30000.ethernet-ffffffff:07, irq=137)
[ 60.920867] Microchip KSZ9131 Gigabit PHY 11c40000.ethernet-ffffffff:07: attached PHY driver
[Microchip KSZ9131 Gigabit PHY] (mii_bus:phy_addr=11c40000.ethernet-ffffffff:07, irq=138)
[ 61.017924] usbusb3: root hub lost power or was reset
[ 61.018018] usbusb1: root hub lost power or was reset
[ 61.105918] usbusb4: root hub lost power or was reset
[ 61.106020] usbusb2: root hub lost power or was reset
[ 61.309991] OOM killer enabled.
[ 61.313131] Restarting tasks ...
[ 61.313647] usb2-1: USB disconnect, device number 2
[ 61.334271] done.
[ 61.352163] PM: suspend exit
[ 61.619922] usb2-1: new high-speed USB device number 3 using ehci-platform
[ 61.788714] hub 2-1:1.0: USB hub found
[ 61.798400] hub 2-1:1.0: 4 ports detected
root@smarc-rzg3s:~#
```

5. Sequence Diagram of AWO Example Project

5.1 Brief Sequence of AWO Example Project

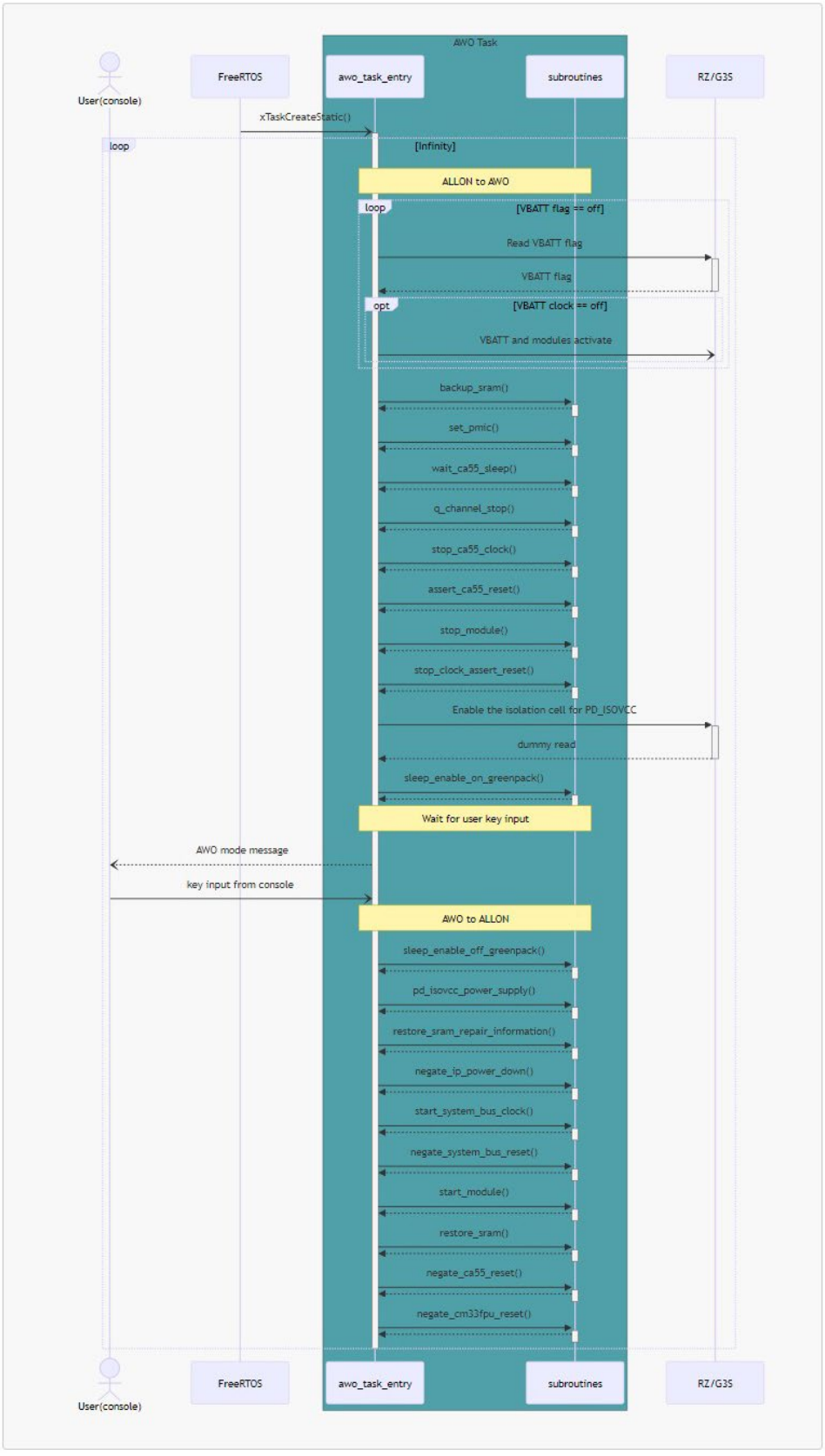

Figure 5.1 Brief Sequence of AWO Example Project

5.2 Suspend Sequence of TF-A

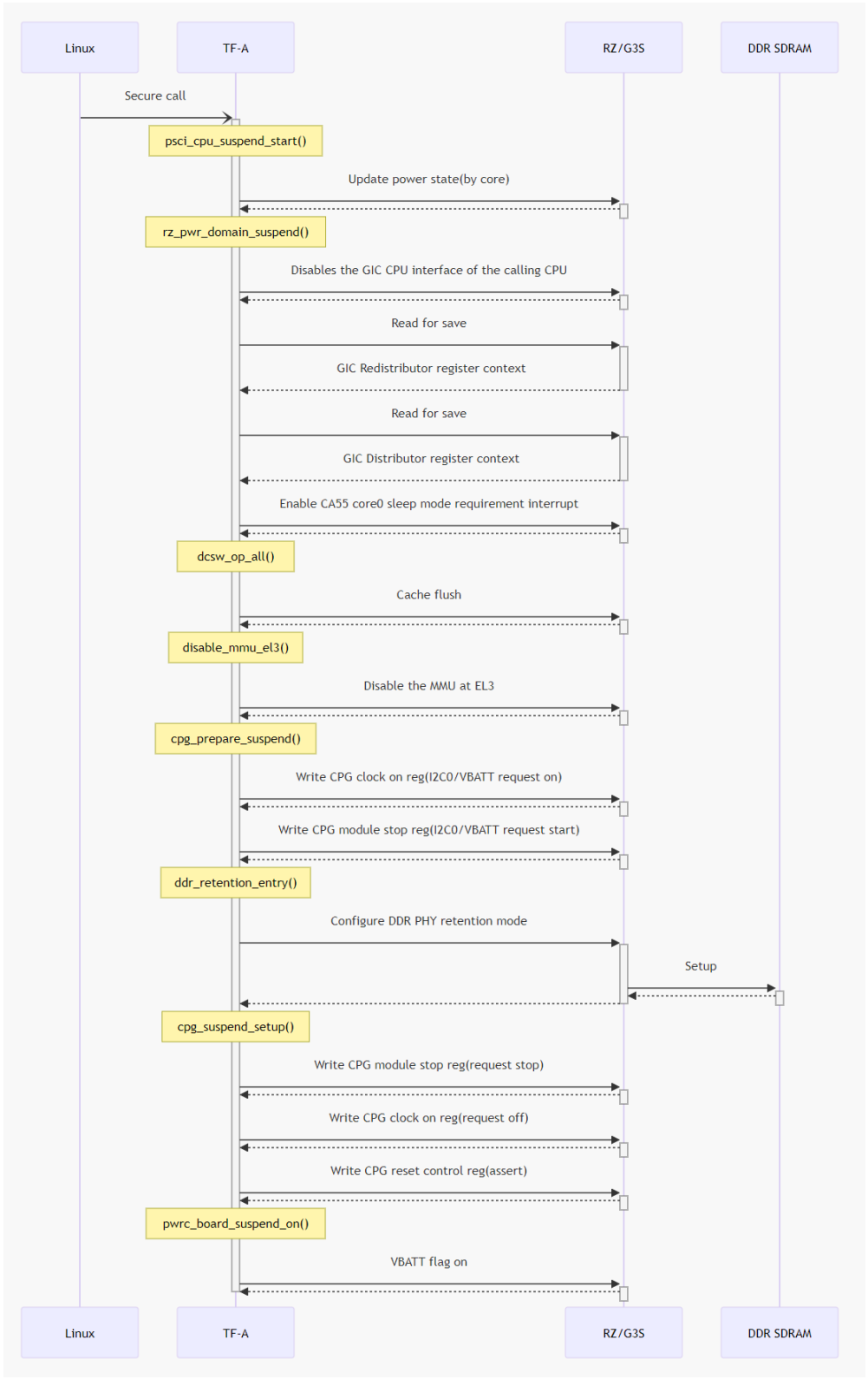

Figure 5.2 TF-A Suspend Sequence

5.3 Resume Sequence of TF-A

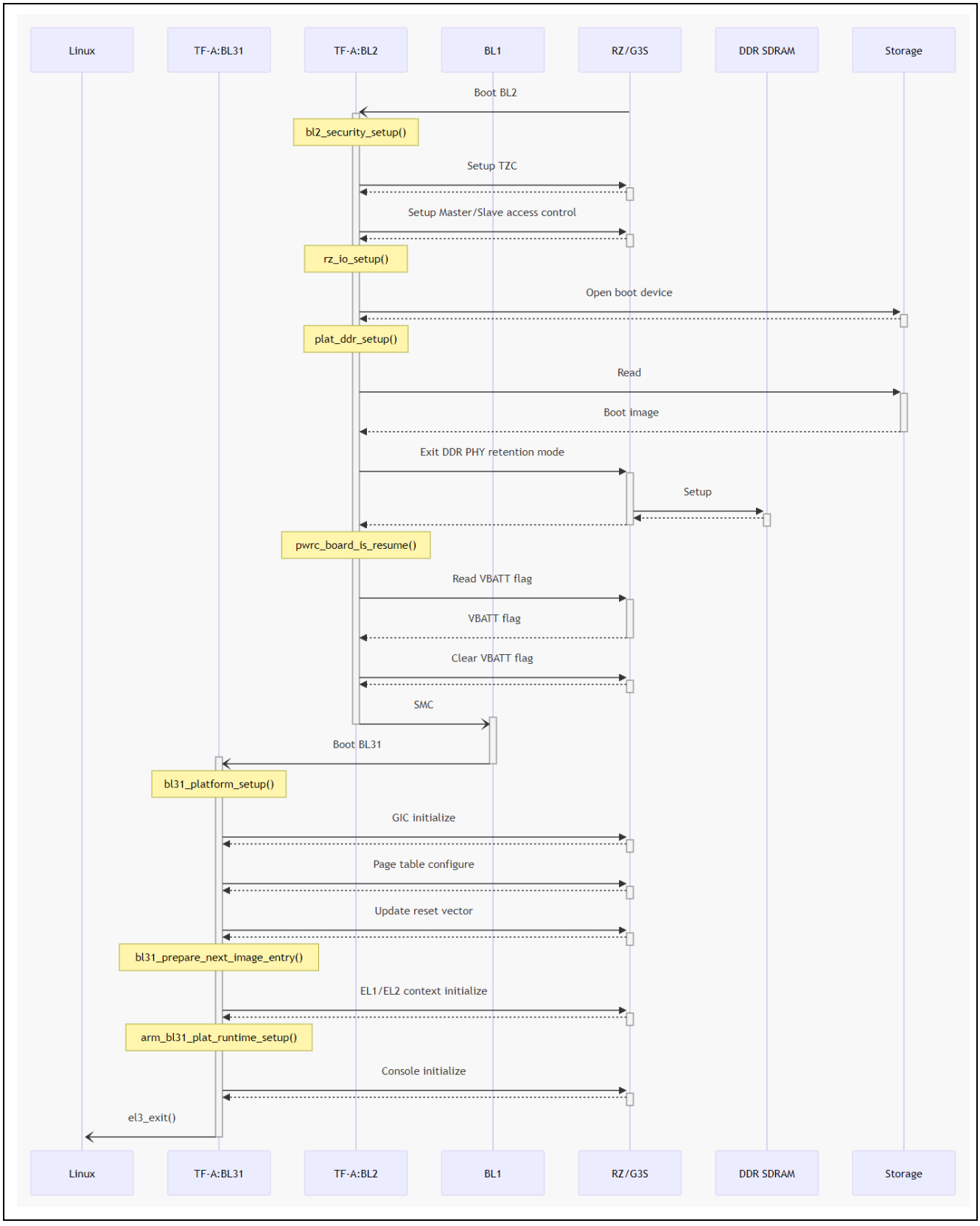

Figure 5.3 TF-A Suspend Sequence

6. Assignment of peripherals for AWO mode

On RZ/G3S, only the peripherals which belong to PD_VCC domain can continue to work under AWO mode. For details, please refer to 41. Low Power Consumption in RZ/G3S Group User's Manual. Table 6.1 shows the expected assignment of peripherals to main core (CA55) and sub core (CM33) on this example project.

Table 6.1 Peripherals assignment on AWO Example Project

Peripherals	CPU		Remarks
	Main core CA55	Sub core CM33	
ADC	X		
CANFD		X	
DMA (Non Secure)	X		
DMA (Secure)		X	
GPT	X		
I2C	X		
I3C	X		
MTU3	X		
POE	X		
POEG	X		
SCI	X		
SCIF	ch0, ch2-5	ch1	Assumed use case of SCIF ch1 on CM33 is to get Pmod USBUART to be worked for the console dedicated to CM33.
SPDIF	X		
RSPI	ch1-4	ch0	Assumed use case of RSPI ch0 on CM33 is to get Pmod SF3 to be worked on RZ/G3S Smarc EVK.
SSI	X		
TSU	X		
WDT	ch0	ch1, ch2	
GTM	ch4-7	ch0-3	
xSPI	X		

7. Function Reference of AWO Example Project

7.1.1 awo_task_entry

```
void awo_task_entry (void *pvParameters)
```

- **Parameters**
  - pvParameters
    Pointer to the parameter passed to AWO task.

- **Returns**
  None

- **Description**
  This function is the entry function of AWO task.
  Here is the overview of processing flow:
  1. Set up timer.
  2. Wait until Arm® Cortex®-A55 (hereinafter referred to as CA55) Linux enters Suspend-to-RAM.
  3. Configure RZ/G3S and PMIC as AWO.
  4. Wait until key input to console is issued.
  5. Configure RZ/G3S and PMIC as ALLON.
  6. Return to 2.

7.1.2 backup_sram

```
static void backup_sram(uint32_t *sys_ca55_cfg_rval_back,
                        uint32_t *sys_ca55_cfg_rvah_back)
```

- **Parameters**
  - sys_ca55_cfg_rval_back
    Pointer to the buffer where lower 32-bit of reset vector base address is stored.
  - sys_ca55_cfg_rvah_back
    Pointer to the buffer where upper 32-bit of reset vector base address is stored.

- **Returns**
  None

- **Description**
  This function first copies the contents in SRAM ACPU0 to the dedicated area in SRAM MPU1. Then, CA55 reset vector address should be copied to the buffer specified by the parameters.
  The reset vector base address will be restored when transiting from AWO to ALLON mode for the resume of CA55 Linux.

7.1.3 set_pmic

```
static void set_pmic(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Configure Power Management IC (PMIC) RAA215300A2GNP#HA3 mounted on RZ/G3S SMARC EVK specific to AWO mode.

7.1.4 wait_ca55_sleep

```
static void wait_ca55_sleep(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**

Issue the request to CA55 Linux to transit to sleep state and wait until the transition is completed.

7.1.5 q_channel_stop

```
static void q_channel_stop(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Stop clock supply to peripheral clock domain and bus bridge via Q-Channel.

7.1.6 stop_ca55_clock

```
static void stop_ca55_clock(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Stop the clock supply to CA55.

7.1.7 assert_ca55_reset

```
static void assert_ca55_reset(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Carry out reset assertion of CA55.

7.1.8 stop_module

```
static void stop_module(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Transit all the modules assigned to the registers listed below to Module Stop State:
  - MSTOP Register ACPU (CPG_BUS_ACPU_MSTOP)
  - MSTOP Register PERI_COM (CPG_BUS_PERI_COM_MSTOP)
  - MSTOP Register PERI_DDR (CPG_BUS_PERI_DDR_MSTOP)
  - MSTOP Register TZCDDR (CPG_BUS_TZCDDR_MSTOP)
  - MSTOP Register MHU (CPG_MHU_MSTOP)
  - Power Down MSTOP Register (CPG_PWRDN_MSTOP)

7.1.9 stop_clock_assert_reset

```
static void stop_clock_assert_reset(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Stop the clock supply assigned to the registers listed below:
  - Clock Control Register AXI_ACPU_BUS (CPG_CLKON_AXI_ACPU_BUS)
  - Clock Control Register AXI_COM_BUS (CPG_CLKON_AXI_COM_BUS)
  - Clock Control Register PERI_COM (CPG_CLKON_PERI_COM)
  - Clock Control Register PERI_DDR (CPG_CLKON_PERI_DDR)
  - Clock Control Register AXI_TZCDDR (CPG_CLKON_AXI_TZCDDR)
  - Clock Control Register Cortex-M33 (hereinafter referred to as CM33) (CPG_CLKON_CM33)
  - Power Down IP Register 1 (CPG_PWRDN_IP1)
  - Power Down IP Register 2 (CPG_PWRDN_IP2)

  Configure the unit clock associated with the register below as Power Down mode:
  - Power Down CLKON Register (CPG_PWRDN_CLKON)

  Cofigure the reset pin associated with the register below as Power Down mode:
  - Power Down RST Register (CPG_PWRDN_RST)

  Assert the reset signal associated with the registers listed below:
  - Reset Control Register AXI_ACPU_BUS (CPG_RST_AXI_ACPU_BUS)
  - Reset Control Register AXI_COM_BUS (CPG_RST_AXI_COM_BUS)
  - Reset Control Register PERI_COM (CPG_RST_PERI_COM)
  - Reset Control Register AXI_TZCDDR (CPG_RST_AXI_TZCDDR)

  Turn off the USB Region Power by configuring USB PWRRDY Register (SYS_USB_PWRRDY).
  Assert PCI_ARESETN reset signal with SYS_PCIE_RST_RSM_B and wait until it's actually asserted by monitoring Reset Monitor Register PCI (CPG_RSTMON_PCI register.

7.1.10 sleep_enable_on_greenpack

```
static void sleep_enable_on_greenpack(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Configure Sleep Enable of GreePAK (SLG7RN46131) connected with RIIC ch1 as ON.

7.1.11 sleep_enable_off_greenpack

```
static void sleep_enable_off_greenpack(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Configure Sleep Enable of GreePAK (SLG7RN46131) connected with RIIC ch1 as OFF.

7.1.12 wait_pd_isovcc_stable

```
static void wait_pd_isovcc_stable(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Wait for the power supply for PD_ISOVCC from PMIC. In the current sample program, 5 msec wait is inserted as an example. Then, DDR is turned on.

7.1.13 pd_isovcc_power_supply

```
static void pd_isovcc_power_supply(void)
```

- Parameters
  None

- **Returns**
  None

- **Description**
  Disable the isolation cell for PD_ISOVCC.

7.1.14 restore_sram_repair_information

```
static void restore_sram_repair_information(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Restore SRAM repair information.

7.1.15 negate_ip_power_down

```
static void negate_ip_power_down(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Negate Power Down mode of IPs assigned to PD_ISOVCC region.

7.1.16 start_system_bus_clock

```
static void start_system_bus_clock(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Start the clock supply to System Bus and Peripherals assigned to PD_ISOVCC region.

7.1.17 negate_system_bus_reset

```
static void negate_system_bus_reset(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Negate reset signal of System Bus and Peripherals assigned to PD_ISOVCC region.

7.1.18 start_module

```
static void start_module(void)
```

- **Parameters**
  None

- **Returns**
  None

- **Description**
  Transmit Peripherals assigned to PD_ISOVCC from Module Stop State to Normal Operation state.

7.1.19 restore_sram

```
static void restore_sram(volatile uint32_t *dummy_read)
```

- **Parameters**
  - dummy_read
    Pointer to the buffer where SRAM ACPU0 data to be backed up by backup_sram function is stored.

- **Returns**
  None

- **Description**
  Restore SRAM ACPU0 data that was backed up by backup_sram function. Be sure to call this function after backup_sram is invoked. Otherwise, the data copied to SRAM_ACPU0 should be unpredictable.

7.1.20 negate_ca55_reset

```
static void negate_ca55_reset(uint32_t sys_ca55_cfg_rval_back,
                              uint32_t sys_ca55_cfg_rvah_back)
```

- **Parameters**
  - sys_ca55_cfg_rval_back
    Lower 32-bit of reset vector address to be backed up by backup_sram function.
  - sys_ca55_cfg_rval_back
    Upper 32-bit of reset vector address to be backed up by backup_sram function.

- **Returns**
  None

- **Description**
  Start the clock supply to CA55 and then carry out the reset release of CA55.

8. Appendix

8.1 Debugging CM33 AWO Example Project from e2studio

This chapter describes how to debug an AWO example project from e2studio.

If you want to debug from e2studio, you need to rebuild TF-A. Follow the steps below to recreate the TF-A.

1. If you build RZ/G VLP v3.0.7, at Step 3 of "**3.2.1 RZ/G VLP Setup**"
Uncomment only the following line in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg3s/meta-rzg3s-vlp3/conf/layer.conf** for enabling AWO support:

```
#MACHINE_FEATURES_append = " RZ_REMOTEPROC"
#MACHINE_FEATURES_append = " RZ_CM33_FIRMWARE_LOAD"
#MACHINE_FEATURES_append = " RZ_CM33_COLDBOOT"
MACHINE_FEATURES_append = " RZ_AWO_SUPPORT"
```

If you build RZ MPU VLP v4.0.1, at Step 3 of "**3.2.2 RZ/G VLP Setup**"
Uncomment only the following line in **meta-rz-features/meta-rz-multi-os/meta-rzg/meta-rzg3s/meta-rzg3s-vlp4/conf/layer.conf** for enabling AWO support:

```
#MACHINE_FEATURES:append = " RZ_REMOTEPROC"
#MACHINE_FEATURES:append = " RZ_CM33_FIRMWARE_LOAD"
#MACHINE_FEATURES:append = " RZ_CM33_COLDBOOT"
MACHINE_FEATURES:append = " RZ_AWO_SUPPORT"
```

2. Write the rebuilt TF-A to the board according to **3.4 How to deploy AWO Example Project.**

Once you have completed the above preparations, open the AWO project in e2studio and start debugging by following the steps:

1. Configure the debugger for **freertos_w_awo_rzg3s_evk_example** project from **Run** > **Debug Configurations...**.

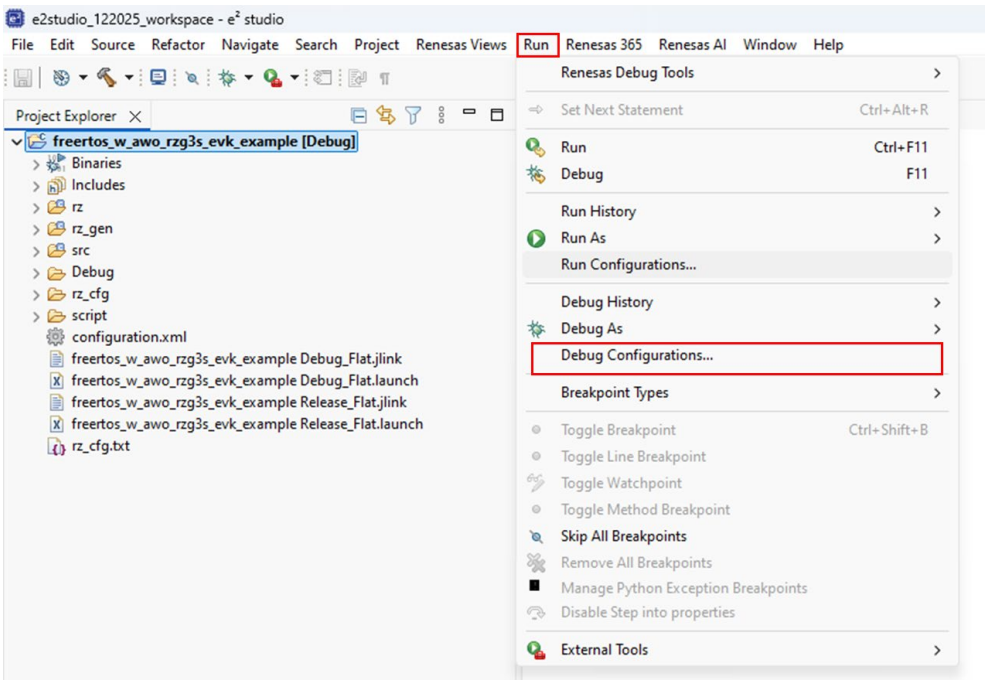

Figure 8.1 Debug Configuration of CM33 AWO Example Project (1)

2. Extract **Renesas DGB Hardware Debugging**, choose **freertos_w_awo_rzg3s_evk_example Debug_Flat** or **Release_Flat** and click **Debug**.

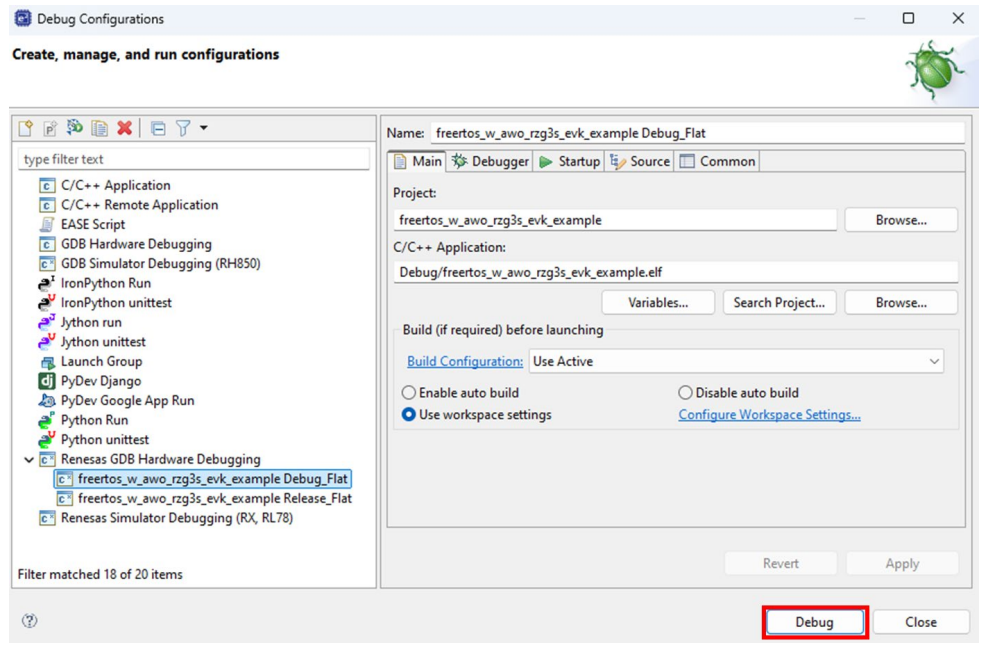

Figure 8.2 Debug Configuration of CM33 AWO Example Project (2)

3. Now the load module of CM33 AWO Example Project has been loaded and Program Counter (PC) should indicate the top of **Entry_Function_S** function. Then, click **Run** > **Run** to continue the invocation.

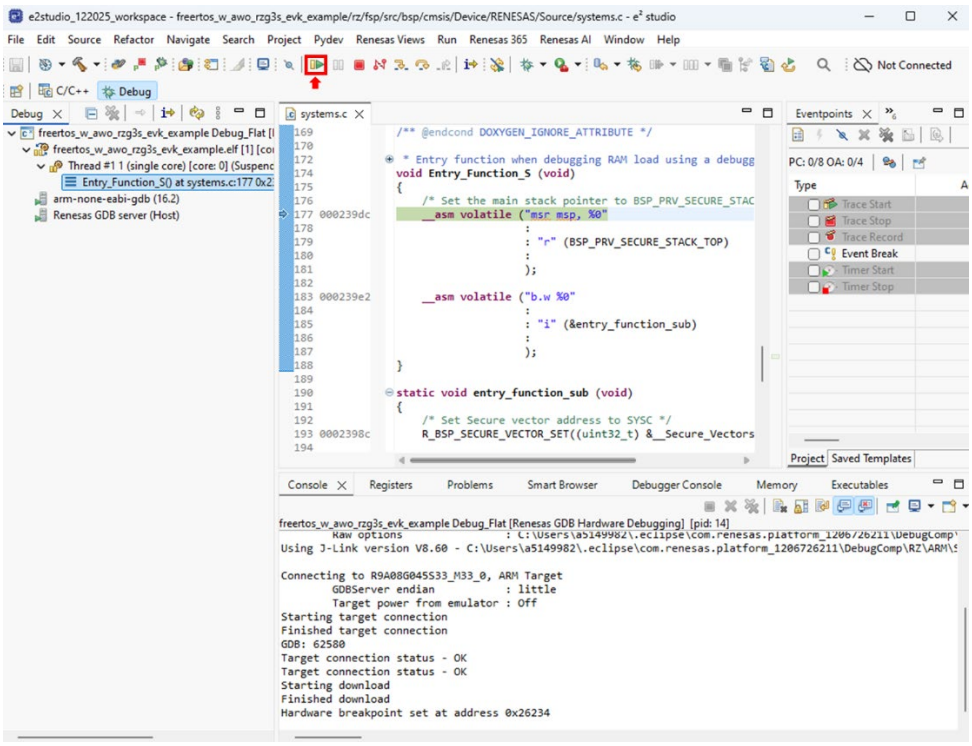

Figure 8.3 Run CM33 AWO Example Project (1)

4. Program should stop at the top of main function. Click Run > Run again to continue. Now, CM33 AWO Example Program should be working.

5. Log in to Linux as **root** user.

8.2 Restrictions

This AWO Example environment has the following restrictions regarding the boot mode.

- CM33 coldboot is not supported. Use this environment with CA55 coldboot.
- eSD boot is not supported.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jul.31.24	-	1st revision issued.
1.01	Sep.30.24	3	Updated the deliverables stated in Table 1-1.
		3	Updated 3.2 RZ/G VLP Setup in accordance with the update of deliverables.
1.02	Apr.25.25	3	Updated the deliverables stated in Table 1-1.
		3-10	Added a process to apply RZ/G Multi-OS Package to the setup procedure.
		26	Added boot mode restriction.
2.00	Jul.22.25	3	Updated the deliverables stated in Table 1-1.
		3	Updated 3.2 RZ/G VLP Setup in accordance with the update of deliverables.
		7-8	Updated the address specified for the SerialFlashWriter to match the latest version.
2.01	Dec.26.25	4	Added instructions for running multiOS with VLP v4.0.1.
2.02	Feb.06.26	-	Update Multi-OS package version to 3.2.0.
4.00	Mar.31.26	-	Update Multi-OS package version to 4.0.0.
4.10	Jun.30.26	-	Update Multi-OS package version to 4.1.0.
4.20	Sep.03.26	-	Update Multi-OS package version to 4.2.0.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
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